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Embedded USB Mass Storage Drive (e230) Features

Embedded USB Mass Storage Drive (e230)

MTFDCAE002SAJ

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Features

- Micron® NAND Flash
 - Interface: Universal Serial Bus (USB) Specification, Revision 2.0
 - USB support
 - USB Specification, Revisions 2.0, 1.1
 - USB Mass Storage Class Specification, Revision 1.0
 - Performance
 - Sequential READ¹: 30 MB/s
 - Sequential WRITE¹: 22 MB/s (2GB and 4GB); 28 MB/s (8GB and 16GB)
 - Reliability: >1 million device hours mean time between failure (MTBF)
 - Endurance: useful operating life of at least 5 years under the following conditions:
 - 8760 power-on hours per year
 - Active 100% of power-on hours
 - Typical operating conditions²: 2GB module: 16 GB/day; 4GB module: 32 GB/day; 8GB module: 64 GB/day; 16GB module: 128 GB/day
 - Static and dynamic wear-leveling
 - 15-bit error correction code (ECC)
 - Password protection
 - Reliability reporting
- Capacity (unformatted)³: 2GB, 4GB, 8GB, or 16GB
 - Form factor
 - Standard (36.9mm x 26.6mm x 9.6mm)
 - Voltage: 5V ±5%
 - Operating temperature
 - Commercial (0°C to +70°C)
 - Industrial (-40°C to +85°C)

- Notes:
1. Typical transfer rate measured with H2BENCH 3.6.
 2. Assumes that 70% of total usable drive capacity contains static files.
 3. 1GB = 1 billion bytes; formatted capacity is less.

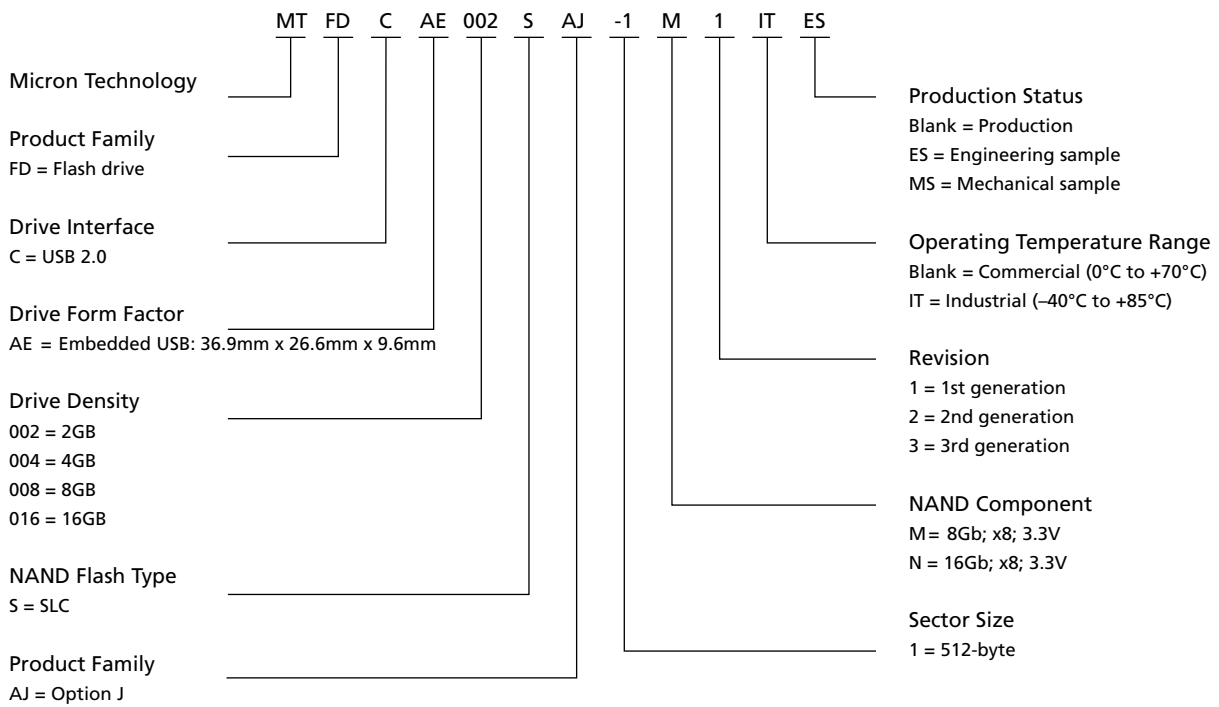


Embedded USB Mass Storage Drive (e230) Features

Part Numbering Information

Micron's RealSSD™ embedded USB drives are available in different configurations and densities. Visit www.micron.com for a list of valid part numbers.

Figure 1: Part Number Chart





Embedded USB Mass Storage Drive (e230) General Description

General Description

Micron RealSSD™ embedded universal serial bus (USB) mass storage drives provide 2GB, 4GB, 8GB, or 16GB of USB 2.0-compatible memory storage in a small form factor. The embedded USB drive is an ideal solution for applications that require low cost and high reliability. Typical applications include PC caching and boot drives for embedded computing, server, and networking systems.

High performance, reliability, and easy implementation make Micron RealSSD embedded USBs an ideal storage solution. To consistently deliver the best possible performance, the embedded USB uses only SLC NAND Flash, and all densities use two x8 NAND channels to the controller. In addition to being fast, SLC NAND Flash offers solid reliability, coupled with ECC and wear leveling. The USB system interface is widely available in many system designs and is easy to implement, enabling rapid time to market.

The embedded USB consists of two TSOP-packaged Micron NAND Flash components, a USB controller, and a 10-pin USB connector on a PCB. Different densities are available depending on the number of die in each package and the density of each NAND Flash die. The drive operates at 5V ±5%. It uses industry-standard 10-pin connectors and supports USB Specification, Revision 2.0. It is also backward compatible with Revision 1.1 and can be used with operating systems that support USB Mass Storage Class Specification, Revision 1.0.

Figure 2: Functional Block Diagram

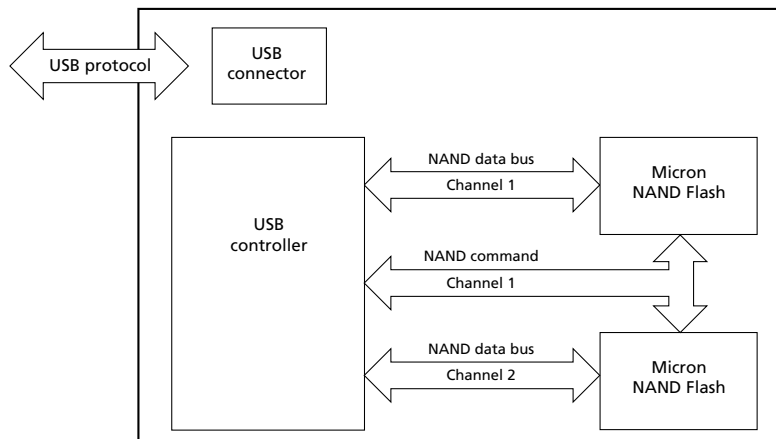


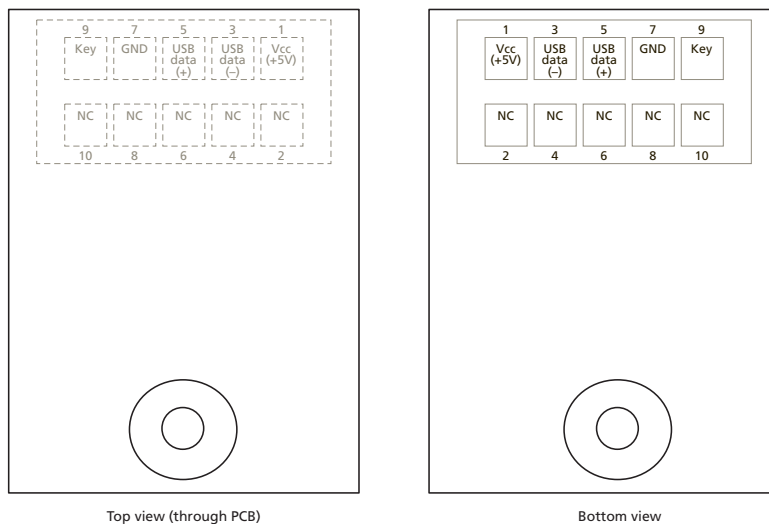
Table 1: Nominal Package Dimensions, Density, and Weight

	Value	Unit
Height	9.6	mm
Width	26.6	mm
Length	36.9	mm
Density	1, 2, 4, 8	GB
Unit weight	4.5	g



**Embedded USB Mass Storage Drive (e230)
 General Description**

Figure 3: Pin Assignments: 2 x 5 Connector



Note: 1. Diagram not to scale.

Table 2: Signal/Pin Descriptions

Symbol	Type	Function
USB data (+), USB data (-)	I/O	Data inputs/outputs: The bidirectional I/Os transfer address, data, and instruction information. Data is output only during READ operations; at other times the I/Os are inputs.
V _{CC}	Supply	V _{CC} power supply pin.
V _{SS}	Supply	V _{SS} ground connection
NC	–	No connect: NC pins are not internally connected. These pins can be driven or left floating.
Key	–	This pin is keyed.



Embedded USB Mass Storage Drive (e230) Error Management

Error Management

The RealSSD™ embedded USB incorporates advanced technology for defect and error management. It uses various combinations of hardware-based error correction algorithms and firmware-based wear-leveling algorithms.

Over the life of the drive, uncorrectable errors may occur. An uncorrectable error is defined as data that is reported as successfully programmed to the drive, but when it is read out of the drive, the data differs from what was programmed. See the Uncorrectable Bit Error Rate Table.

The mean time between failures (MTBF) can be predicted based on component reliability data obtained by following the methods referenced in the Telecordia SR-332 reliability prediction procedures for electronic equipment.

Table 3: System Reliability

Density	MTFB (Operating Hours)
2–16GB	>1 million device hours

Table 4: Uncorrectable Bit Error Rate

Uncorrectable Bit Error Rate (BER) ¹	Operation
<1 bit error in 10 ¹⁵ bits	READ

Note: 1. BER is measured with a WRITE-to-READ ratio of 1:1.



Embedded USB Mass Storage Drive (e230) Electrical Characteristics

Electrical Characteristics

Stresses greater than those listed may cause permanent damage to the drive. This is a stress rating only, and functional operation of the drive at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

Table 5: Absolute Maximum Ratings

Parameter/Condition	Symbol	Min	Max	Unit
V _{CC} supply voltage	V _{CC}	-0.6	5.25	V

Table 6: DC and Operating Characteristics

Parameter/Condition	Symbol	Min	Typ	Max	Unit	Condition
Standby current	I _{sb}	-	50	60	mA	V _{CC} = 5V
Active current	I _{CC1}	-	100	120	mA	V _{CC} = 5V

Table 7: Recommended Operating Conditions

Parameter/Condition	Symbol	Min	Typ	Max	Unit	
Operating temperature	Commercial	T _A	0	-	70	°C
	Industrial		-40	-	85	°C
V _{CC} supply voltage	V _{CC}	4.75	5.00	5.25	V	
Ground supply voltage	V _{SS}	0	0	0	V	

Table 8: Shock and Vibration

Parameter/Condition	Specification
Shock	1500g/0.5ms
Vibration	5-500Hz at 3.1G



Embedded USB Mass Storage Drive (e230) Compliance

Compliance

Micron RealSSD embedded USB drives comply with the following requirements:

- CE (Europe): EN55022, 2006 Class B and EN55024, 1998 + A1: 2001 + A2:2003
- FCC: CFR Title 47, Part 15, ICES-003, all Class B
- UL (US): approval to UL-60950-1, 2nd Edition, 2007-03-27, IEC 60950-1:2005, 2nd Edition
- RoHS, "green" package



Embedded USB Mass Storage Drive (e230) Mechanical Information

Mechanical Information

The 10-pin (2 x 5) female electrical connector has a height of 7.4mm, a pitch of 2.54 mm, and supports the standard USB 2.0 interface. A mounting hole is also provided on the PCB for a stable, reliable connection to the mounting board.

The motherboard pin headers listed in Table 9 are compatible with Micron's RealSSD embedded USB drives. Pin headers that are not listed may also be compatible.

Table 9: Compatible Pin Headers

Manufacturer	Part Number	Type
Pinrex	212-92-05GB01	SMT
	210-92-05GB01	Straight
Amtek	PHIF525-205GB	Press fit
	PHIS25-205GB	Straight

Reference Documents

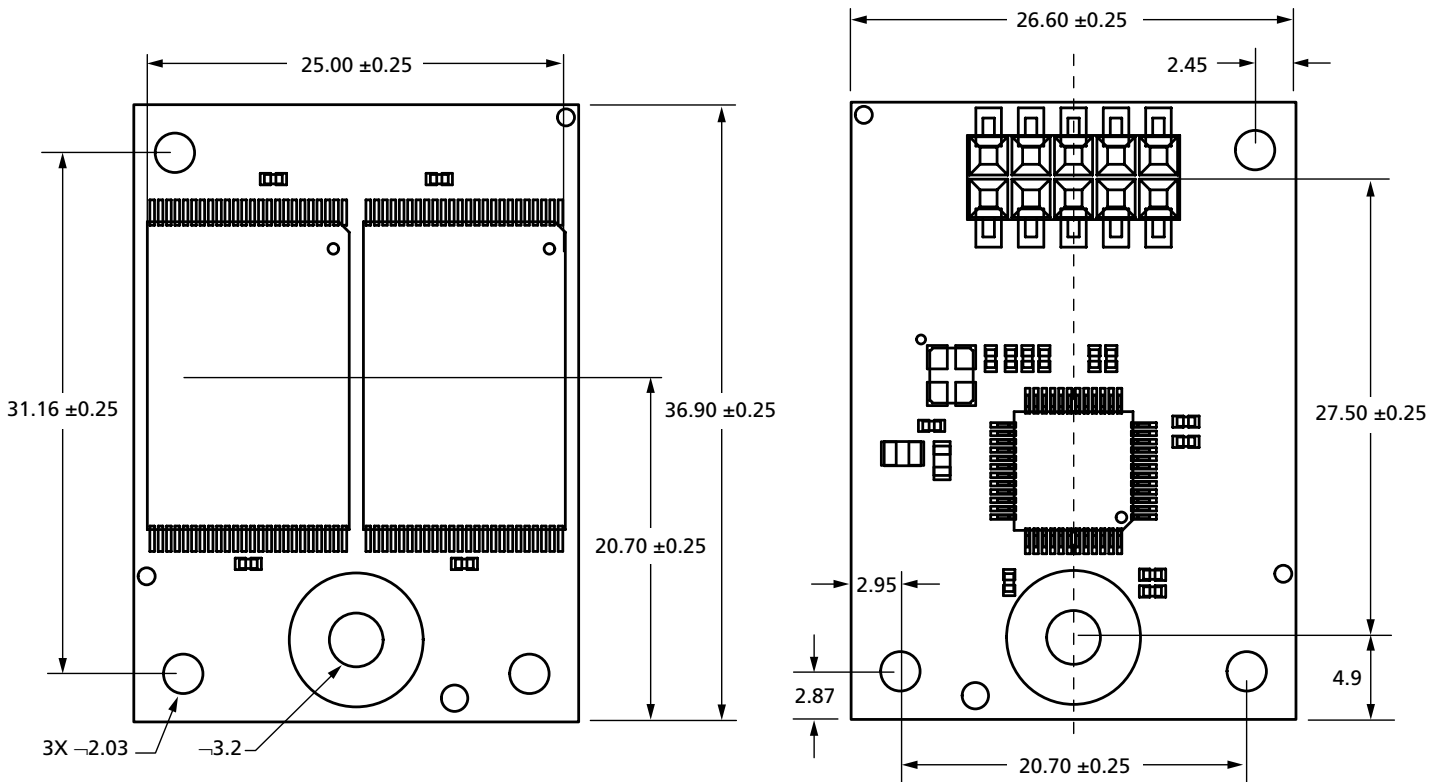
Reference documentation for the USB 2.0 standard (USB 2.0 specification, technical documents, compliance test procedures, and other related documents) can be found at www.usb.org/developers/docs.



**Embedded USB Mass Storage Drive (e230)
 Package Dimensions**

Package Dimensions

Figure 4: Embedded USB Package



Note: 1. All dimensions are in millimeters.

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This data sheet contains minimum and maximum limits specified over the power supply and temperature range set forth herein. Although considered final, these specifications are subject to change, as further product development and data characterization sometimes occur.